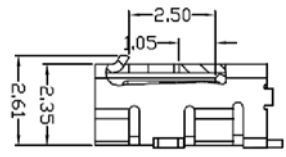
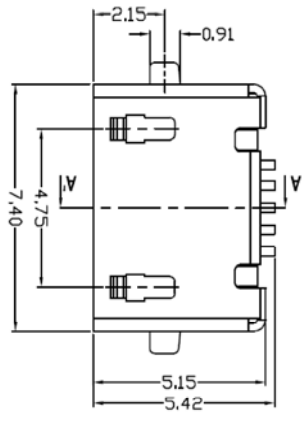
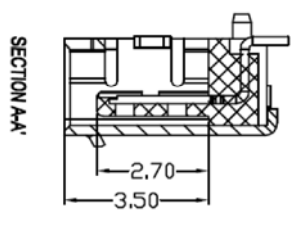
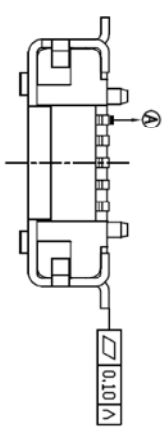
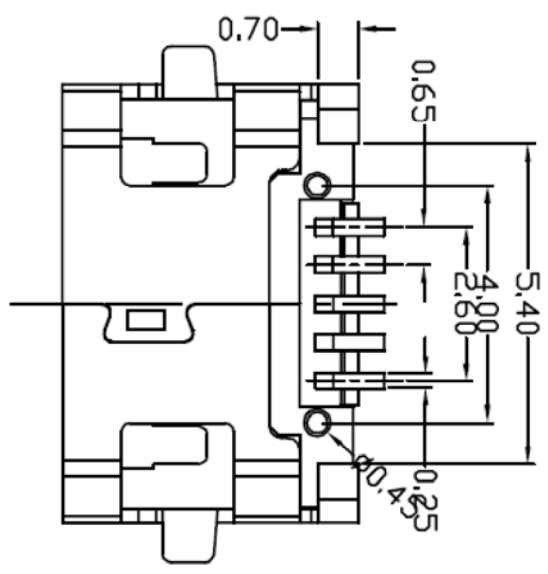
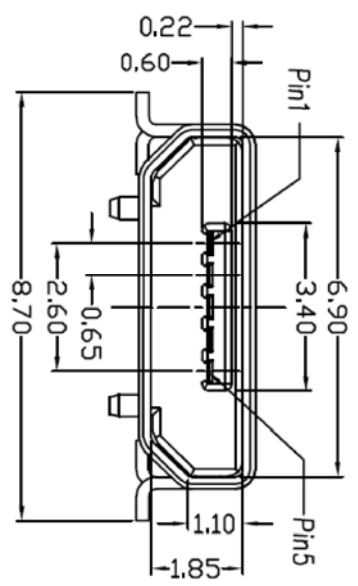
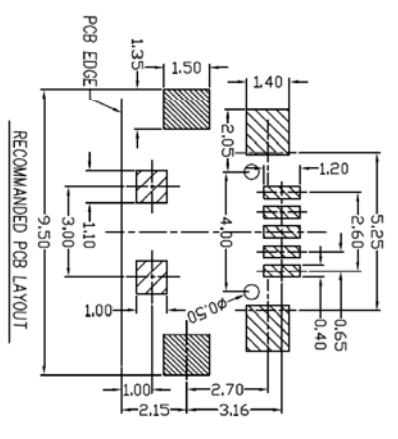


REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	CHANGER



**Notes:**

1. Materials:
  - 1.1 Housing: High temperature thermoplastic with g.f.; UL94 v-0.
  - 1.2 Contact: copper alloy; t=0.20mm.
  - 1.3 Shell: copper alloy; t=0.25mm.
2. Specifications:
  - 2.1. Current rating: 1 A Max.
  - 2.2. Dielectric withstanding voltage: 100 V(ac) for 1 min.
  - 2.3. Contact resistance: 50 mW Max.
  - 2.4. Insulation resistance: 100 MW Min.
  - 2.5. Total mating force: 3.57 Kgf Max.
  - 2.6. Total unmating force: 1.0 Kgf Min 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
  - 2.7. Temperature range: -30°C~+80°C



GENERAL TOLERANCE		鉅創科技有限公司 TRONTPEK TECHNOLOGY CO., LTD.	
X ± 0.45	X* ± 2°	TITLE: MICRO USB 5S B 型四腳全貼定位有外殼加單腳長8.7	
X ± 0.40	X* ± 1°		
.XX ± 0.30	.XX* ±		
XXX ± 0.15	.XXX* ±	PART NO.: TMU-02-07-N48	

CUSTOMER DRAWING			
APPROVED	CHECKED:	DRAWN:	DATE:
tony	tony	sam	mm
SCALE: 1:1		SHEET: 1 / 1	
DRAWN:		REV: A	

1 2 3 4 5 6 7 8 9 10 11 12

A B C D E F G H I J